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(19) **United States**(12) **Patent Application Publication**
LI et al.(10) **Pub. No.: US 2022/0377906 A1**(43) **Pub. Date: Nov. 24, 2022**(54) **CIRCUIT BOARD WITH AT LEAST ONE
EMBEDDED ELECTRONIC COMPONENT
AND METHOD FOR MANUFACTURING
THE SAME**(71) Applicants: **Avary Holding (Shenzhen) Co.,
Limited., Shenzhen (CN); QING
DING PRECISION ELECTRONICS
(HUAIAN) CO.,LTD, Huai an (CN);
GARUDA TECHNOLOGY CO.,
LTD., New Taipei (TW)**(72) Inventors: **JIA-HE LI, Shenzhen (CN);
YONG-CHAO WEI, Qinhuangdao
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ABSTRACT

A method for manufacturing a circuit board including the following steps: providing a flexible double-sided metal-clad laminate including a first metal foil, a flexible dielectric layer, and a second metal foil. A carrier is attached to the second metal foil. A first wiring layer including a first wiring region and a second wiring region is formed by the first metal foil. The first wiring region includes a first connecting pad, and the second wiring region includes a connecting pad. A plurality of rigid dielectric blocks surrounded to form an interval and a first groove exposing the first connecting pad is pressed on the flexible dielectric layer to form a rigid dielectric layer. An electronic component is fixed the first groove. The carrier is removed. The intermediate structure is bent along the interval and pressed. A second wiring layer is formed by the second metal foil.

